

ARK Home



Intel® QM87 Chipset

(Intel® DH82QM87 PCH)

SPECIFICATIONS

Essentials

Graphics Specifications

Expansion Options

I/O Specifications

Package Specifications

Advanced Technologies

Intel® Platform Protection Technology

COMPATIBLE PRODUCTS

ORDERING / SSPECS / STEPPINGS

SPECIFICATIONS

Essentials

Status	Launched
Launch Date	Q2'13
Supported FSBs	N/A
FSB Parity	No
Embedded Options Available	Yes
Lithography	32 nm
Max TDP	2.7 W
Recommended Customer Price	
Product Brief	Link

Graphics Specifications

Integrated Graphics ‡	No
Graphics Output	VGA
Intel® Clear Video Technology	Yes
# of Displays Supported ‡	3
Intel® Insider™	Yes

Expansion Options

PCI Support	No
PCI Express Revision	2.0
PCI Express Configurations ‡	x1, x2, x4
Max # of PCI Express Lanes	8

I/O Specifications

USB Revision	3.0/2.0
USB 3.0	0
USB 2.0	8
Total # of SATA Ports	6
Max # of SATA 6.0 Gb/s Ports	4
RAID Configuration	0/1/5/10
Integrated LAN	No
Integrated IDE	No
Integrated SAS ports	No
PCIe* Uplink	No

Add to Compare

RELATED PRODUCTS

Products formerly Lynx Point



QUICK LINKS

No Datasheet Available
[Export Full Specifications](#)
[Search Distributors](#)
[Support Overview](#)
[Search all of intel.com](#)

PCN/MDDS INFORMATION

SR13G
927364: [PCN](#) | [MDDS](#)
SR17C
929149: [PCN](#) | [MDDS](#)



Package Specifications	
Max CPU Configuration	1
Package Size	20mm x 20 mm x1.573mm
Low Halogen Options Available	See MDDS
Advanced Technologies	
Intel® Virtualization Technology for Directed I/O (VT-d) ‡	Yes
Intel® vPro Technology ‡	Yes
Intel® ME Firmware Version	9.0
Intel® HD Audio Technology	Yes
Intel® Matrix Storage Technology	Yes
Intel® Rapid Storage Technology	Yes
Intel® Smart Connect Technology	Yes
Intel® Smart Response Technology	Yes
Intel® Stable Image Platform Program (SIPP)	Yes
Intel® Small Business Advantage	Yes
Intel® Platform Protection Technology	
Trusted Execution Technology ‡	Yes
Anti-Theft Technology	Yes

All information provided is subject to change at any time, without notice. Intel may make changes to manufacturing life cycle, specifications, and product descriptions at any time, without notice. The information herein is provided "as-is" and Intel does not make any representations or warranties whatsoever regarding accuracy of the information, nor on the product features, availability, functionality, or compatibility of the products listed. Please contact system vendor for more information on specific products or systems.

"Intel classifications" consist of Export Control Classification Numbers (ECCN) and Harmonized Tariff Schedule (HTS) numbers. Any use made of Intel classifications are without recourse to Intel and shall not be construed as a representation or warranty regarding the proper ECCN or HTS. Your company may be the exporter of record, and as such, your company is responsible for determining the correct classification of any item at the time of export.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.


‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

The Recommended Customer Price ("RCP") is pricing guidance for Intel products. Prices are for direct Intel customers and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

WARNING: Altering clock frequency and/or voltage may: (i) reduce system stability and useful life of the system and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance; (iv) cause additional heat or other damage; and (v) affect system data integrity. Intel has not tested, and does not warranty, the operation of the processor beyond its specifications. Intel assumes no responsibility that the processor, including if used with altered clock frequencies and/or voltages, will be fit for any particular purpose. For more information, visit <http://www.intel.com/content/www/us/en/gaming/overclocking/overclocking-intel-processors.html>

 [Send us your feedback!](#)